

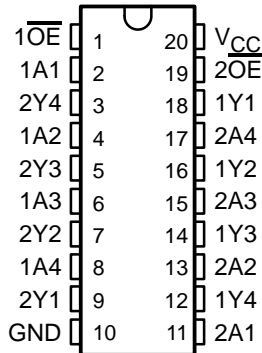
# SN54BCT240, SN74BCT240 OCTAL BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

SCBS004F – OCTOBER 1987 – REVISED MARCH 2003

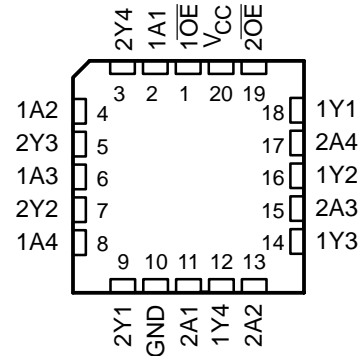
- Operating Voltage Range of 4.5 V to 5.5 V
- State-of-the-Art BiCMOS Design Significantly Reduces  $I_{CCZ}$

- 3-State Outputs Drive Bus Lines or Buffer Memory Address Registers
- ESD Protection Exceeds JESD 22 – 2000-V Human-Body Model (A114-A)

SN54BCT240 . . . J OR W PACKAGE  
SN74BCT240 . . . DB, DW, N, OR NS PACKAGE  
(TOP VIEW)



SN54BCT240 . . . FK PACKAGE  
(TOP VIEW)



## description/ordering information

These octal buffers and line drivers are designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. Together with the 'BCT241 and 'BCT244 devices, these devices provide the choice of selected combinations of inverting and noninverting outputs, symmetrical  $\overline{OE}$  (active-low output-enable) inputs, and complementary OE and  $\overline{OE}$  inputs. These devices feature high fan-out and improved fan-in.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

## ORDERING INFORMATION

$T_A$	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	PDIP – N	Tube	SN74BCT240N	SN74BCT240N
	SOIC – DW	Tube	SN74BCT240DW	
		Tape and reel	SN74BCT240DWR	BCT240
	SOP – NS	Tape and reel	SN74BCT240NSR	BCT240
–55°C to 125°C	SSOP – DB	Tape and reel	SN74BCT240DBR	BT240
	CDIP – J	Tube	SNJ54BCT240J	SNJ54BCT240J
	CFP – W	Tube	SNJ54BCT240W	SNJ54BCT240W
	LCCC – FK	Tube	SNJ54BCT240FK	SNJ54BCT240FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS  
INSTRUMENTS**

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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

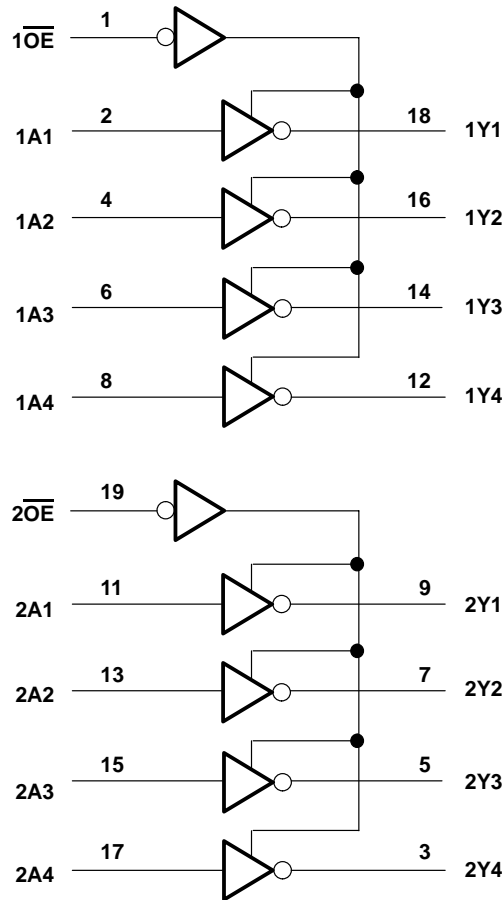
# SN54BCT240, SN74BCT240 OCTAL BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

SCBS004F – OCTOBER 1987 – REVISED MARCH 2003

FUNCTION TABLE  
(each buffer)

INPUTS		OUTPUT
$\overline{OE}$	A	Y
L	H	L
L	L	H
H	X	Z

## logic diagram (positive logic)



# SN54BCT240, SN74BCT240 OCTAL BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

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## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, $V_{CC}$	–0.5 V to 7 V
Input voltage range, $V_I$ (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the disabled or power-off state, $V_O$	–0.5 V to 5.5 V
Voltage range applied to any output in the high state, $V_O$	–0.5 V to $V_{CC}$
Input clamp current, $I_{IK}$	–30 mA
Current into any output in the low state: SN54BCT240	96 mA
SN74BCT240	128 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2): DB package	70°C/W
DW package	58°C/W
N package	69°C/W
NS package	60°C/W
Storage temperature range, $T_{stg}$	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.  
2. The package thermal impedance is calculated in accordance with JESD 51-7.

## recommended operating conditions (see Note 3)

		SN54BCT240			SN74BCT240			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
$V_{CC}$	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
$V_{IH}$	High-level input voltage	2			2			V
$V_{IL}$	Low-level input voltage			0.8			0.8	V
$I_{IK}$	Input clamp current			–18			–18	mA
$I_{OH}$	High-level output current			–12			–15	mA
$I_{OL}$	Low-level output current			48			64	mA
$T_A$	Operating free-air temperature	–55		125	0		70	°C

NOTE 3: All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

# SN54BCT240, SN74BCT240 OCTAL BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		SN54BCT240			SN74BCT240			UNIT
			MIN	TYP†	MAX	MIN	TYP†	MAX	
$V_{IK}$	$V_{CC} = 4.5 V$ ,	$I_I = -18 mA$	-1.2			-1.2			V
$V_{OH}$	$V_{CC} = 4.5 V$	$I_{OH} = -3 mA$	2.4	3.3		2.4	3.3		V
		$I_{OH} = -12 mA$	2	3.2					
		$I_{OH} = -15 mA$				2	3.1		
$V_{OL}$	$V_{CC} = 4.5 V$	$I_{OL} = 48 mA$	0.38 0.55						V
		$I_{OL} = 64 mA$				0.42	0.55		
$I_I$	$V_{CC} = 5.5 V$ ,	$V_I = 7 V$	0.1			0.1			mA
$I_{IH}$	$V_{CC} = 5.5 V$ ,	$V_I = 2.7 V$	20			20			$\mu A$
$I_{IL}$	$V_{CC} = 5.5 V$ ,	$V_I = 0.5 V$	-1			-1			mA
$I_{OZH}$	$V_{CC} = 5.5 V$ ,	$V_O = 2.7 V$	50			50			$\mu A$
$I_{OZL}$	$V_{CC} = 5.5 V$ ,	$V_O = 0.5 V$	-50			-50			$\mu A$
$I_{OS}‡$	$V_{CC} = 5.5 V$ ,	$V_O = 0$	-100		-225	-100		-225	mA
$I_{CCH}$	$V_{CC} = 5.5 V$ ,	Outputs open	19 31			19 31			mA
$I_{CCL}$	$V_{CC} = 5.5 V$ ,	Outputs open	46 71			46 71			mA
$I_{CCZ}$	$V_{CC} = 5.5 V$ ,	Outputs open	6 9			6 9			mA
$C_i$	$V_{CC} = 5 V$ ,	$V_I = 2.5 V$ or $0.5 V$	6			6			pF
$C_o$	$V_{CC} = 5 V$ ,	$V_O = 2.5 V$ or $0.5 V$	11			11			pF

† All typical values are at  $V_{CC} = 5 V$ .

‡ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

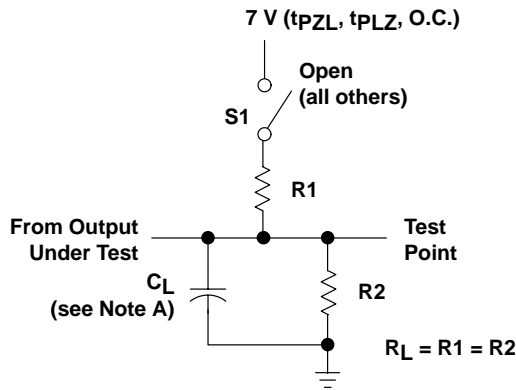
## switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 5 V$ , $C_L = 50 pF$ , $R_1 = 500 \Omega$ , $R_2 = 500 \Omega$ , $T_A = 25^\circ C$			$V_{CC} = 4.5 V$ to $5.5 V$ , $C_L = 50 pF$ , $R_1 = 500 \Omega$ , $R_2 = 500 \Omega$ , $T_A = MIN$ to $MAX$ §				UNIT
			BCT240			SN54BCT240		SN74BCT240		
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$t_{PLH}$	A	Y	0.5	3.3	4.8	0.5	6.4	0.5	5.6	ns
$t_{PHL}$			0.4	1.8	3.5	0.4	4.5	0.4	4	
$t_{PZH}$	$\overline{OE}$	Y	1	6.4	7.9	1	9.2	1	8.8	ns
$t_{PZL}$			1	7.5	9.4	1	10.8	1	10.5	
$t_{PHZ}$	$\overline{OE}$	Y	1	6	6.8	1	8.5	1	8.1	ns
$t_{PLZ}$			1	6.7	8.1	1	10.6	1	9.5	

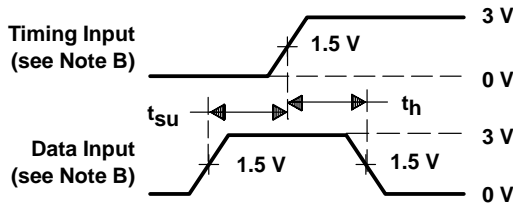
§ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



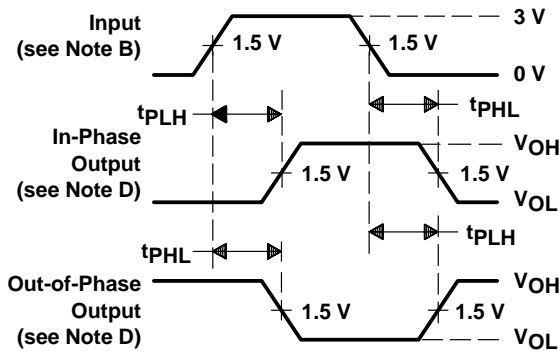
PARAMETER MEASUREMENT INFORMATION



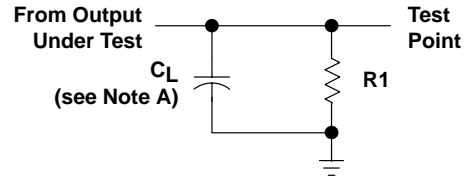
LOAD CIRCUIT FOR  
3-STATE AND OPEN-COLLECTOR OUTPUTS



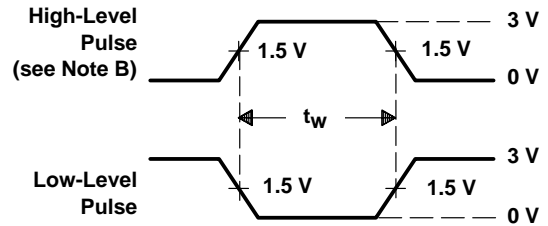
VOLTAGE WAVEFORMS  
SETUP AND HOLD TIMES



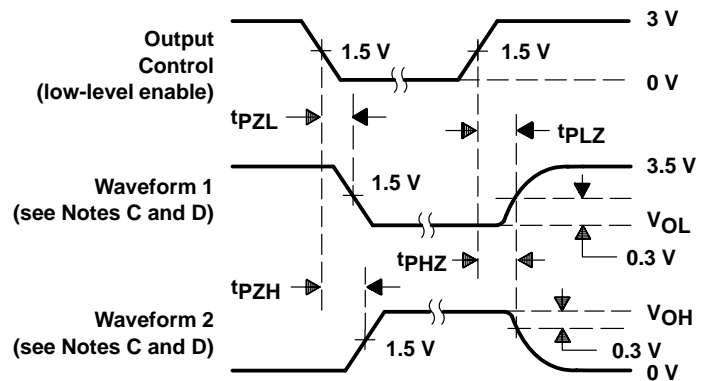
VOLTAGE WAVEFORMS  
PROPAGATION DELAY TIMES (see Note D)



LOAD CIRCUIT FOR  
TOTEM-POLE OUTPUTS



VOLTAGE WAVEFORMS  
PULSE DURATION



VOLTAGE WAVEFORMS  
ENABLE AND DISABLE TIMES, 3-STATE OUTPUTS

- NOTES: A.  $C_L$  includes probe and jig capacitance.  
B. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10$  MHz,  $t_r = t_f \leq 2.5$  ns, duty cycle = 50%.  
C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.  
D. The outputs are measured one at a time with one transition per measurement.  
E. When measuring propagation delay times of 3-state outputs, switch S1 is open.  
F. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9074201M2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9074201M2A SNJ54 BCT240FK	<a href="#">Samples</a>
5962-9074201MRA	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9074201MR A SNJ54BCT240J	<a href="#">Samples</a>
5962-9074201MSA	ACTIVE	CFP	W	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9074201MS A SNJ54BCT240W	<a href="#">Samples</a>
SN74BCT240DW	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	BCT240	<a href="#">Samples</a>
SN74BCT240N	ACTIVE	PDIP	N	20	20	RoHS & Non-Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74BCT240N	<a href="#">Samples</a>
SN74BCT240NSR	ACTIVE	SO	NS	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	BCT240	<a href="#">Samples</a>
SNJ54BCT240FK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9074201M2A SNJ54 BCT240FK	<a href="#">Samples</a>
SNJ54BCT240J	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9074201MR A SNJ54BCT240J	<a href="#">Samples</a>
SNJ54BCT240W	ACTIVE	CFP	W	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9074201MS A SNJ54BCT240W	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of  $\leq 1000$ ppm threshold. Antimony trioxide based flame retardants must also meet the  $\leq 1000$ ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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**OTHER QUALIFIED VERSIONS OF SN54BCT240, SN74BCT240 :**

● Catalog : [SN74BCT240](#)

● Military : [SN54BCT240](#)

NOTE: Qualified Version Definitions:

● Catalog - TI's standard catalog product

● Military - QML certified for Military and Defense Applications

**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74BCT240NSR	SO	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1



**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74BCT240NSR	SO	NS	20	2000	367.0	367.0	45.0

**TUBE**


\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
5962-9074201M2A	FK	LCCC	20	1	506.98	12.06	2030	NA
5962-9074201MSA	W	CFP	20	1	506.98	26.16	6220	NA
SN74BCT240DW	DW	SOIC	20	25	507	12.83	5080	6.6
SN74BCT240N	N	PDIP	20	20	506	13.97	11230	4.32
SNJ54BCT240FK	FK	LCCC	20	1	506.98	12.06	2030	NA
SNJ54BCT240W	W	CFP	20	1	506.98	26.16	6220	NA

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within Mil-Std 1835 GDFP2-F20

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package is hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.



# EXAMPLE BOARD LAYOUT

DW0020A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE  
SCALE:6X



SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



# EXAMPLE STENCIL DESIGN

DW0020A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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